

N109 W13300 ELLSWORTH DRIVE GERMANTOWN, WI 53022
262-253-5900 FAX 262-253-5919

DESCRIPTION:

Resinlab[®] *EP1112NC Clear* is a two part unfilled fast curing electronic grade epoxy encapsulant designed for small to medium sized castings. *EP1112NC Clear* is a modified version of the standard EP1112, which utilizes a higher molecular weight aromatic diluent to significantly reduce the tendency for crystallization in the epoxy resin.

EP1112NC Clear cures completely at room temperature to a tough, flexible polymer. The low viscosity allows for good wicking and penetration into components and circuitry and also will release trapped air. It has very good resistance to water, acids and bases and most organic solvents. Thermal shock and cycling properties are also enhanced by its high elongation giving it the ability to absorb difference in CTE's of substrates.

It was formulated to a 1A:1B volume mix ratio for use in side-by-side dispensing cartridges and meter/mix and dispense equipment. *EP1112NC Clear* will reach full cure at room temperature within 6 to 12 hours. Cure time can be accelerated by the application of heat after product has gelled. Times and temperatures from 1 hour at 65 °C to 10 minutes at 100 °C are typical for small castings (less than 50 grams). Time to heat substrate must be taken into account. Cooler temperatures will also extend work time and increase cure times.

TYPICAL PROPERTIES:

All properties given are at 25 °C unless otherwise noted.

Property:	Value:	Test Method or Source:
Color	Clear	Visual
Mix Ratio	Part A to Part B	Calculated
Mix Ratio by weight	1.20 to 1	
Mix Ratio by volume	1 to 1	
Cure Schedule	6-12 hours @ 25 °C 1 hr @ 65 °C 10 min @ 100 °C	
Viscosity - Part A	1,100 cP	TA HR20 Rheometer 25mm parallel plate @
Viscosity - Part B	800 cP	1/s DCV6100723
Viscosity - Mixed	1,000 cP	
Specific Gravity - Part A	1.14	Calculated
Specific Gravity - Part B	0.96	
Specific Gravity - Mixed	1.05	
Pot Life defined as the time it takes for initial mixed viscosity to double	12 minutes	TA HR20 Rheometer parallel plate 25mm @ 1/s DCV6100723
Gel Time 100cc Sample	16 minutes	455300005339/Gardco Gel Timer
Peak Exotherm	128.5 °C after 26 minutes for 40 mL sample	455300005593 by Type K thermocouple
Hardness	70 Shore D	455300006287/ASTM D2240
Glass Transition Temperature/Tg	23 °C	453560822409 by DSC

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Property:	Value:	Test Method or Source:
Water Absorption	0.1 %	24 hr immersion 457561824543/ASTM D570
Tensile Properties:		4535601224470/ASTM D638
Strength	2,500 psi	
Elongation	45 %	
Modulus	120,000 psi	
Lap Shear Strength		4535601224468/ASTM D1002
0.010" Bond Line, Al to Al	1,300 psi	
Compressive Properties:		4535601224467/ASTM D695
Yield Strength	> 28,000 psi	
Modulus	228,000 psi	
Flame Resistance	Passes with HB Rating @ 6.0 mm	45376013225560/UL94HB
Tested at ResinLab, not UL Certified		
Thermal Conductivity by LFA	0.14 W/m.K *	453560822409/ASTM E1461
Electrical Resistivity:		455300006612/ASTM D257
Volume	3.37 x 10 ¹⁴ ohm-cm	@ 23 °C @ 59 %RH
Surface	8.15 x 10 ¹⁴ ohm/sq	
Dielectric Constant & Dissipation Factor:		455300006513/ASTM D150
@ 100 Hz	3.52, 0.07	
@ 100 kHz	2.89, 0.03	
AC Dielectric Strength	410 V/mil *	DCV6101609; ASTM D149 Method A, immersed in ASTM D3487 Type II Oil
Coefficient of Thermal Expansion by TMA:		455300005340/ASTM E831 TMA, 5 °C/min
below Tg	66 ppm/°C	
above Tg	270 ppm/°C	
Operating Temperature Range	-55 to 150 °C**	
Relative Thermal Index (RTI)	90 °C	UL746B, Table 7.1 Generic Value Based on Composition

* Asterisk denotes values considered typical to associated resin systems or extrapolated from other test results.

** Operating Temperature Range is based on average design requirements and is not intended as a guarantee of suitability for all applications operating at that temperature.

*** This TDS contains values that have been updated. The values reported in this technical data sheet are typical values of the product, and are highly dependent on test conditions and methodology. We actively seek the most precise and accurate ways to measure and interpret performance of our products, and to update estimated values with measured values. The formula has not been revised or changed in any way. Although the values on paper have changed, you can expect the same performance of the product.

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INSTRUCTIONS:

1. Bring to room temperature prior to use.
2. Cartridge format: Mixer should be attached keeping the cartridge vertical and any air pocket purged this way. After the mixer contains material, the mixer tip can be dropped to dispense pre-bleed amount. Attach a new static mixer with each cartridge, then pre-bleed the first 3 inches of dispensed material or until a uniform color is obtained. Maintain adequate velocity during dispensing to ensure complete mixing.
3. Bulk format: stir until homogeneous weigh and mix parts A and B accurately and thoroughly, scraping sides of container often. Do not pour from mixing container, transfer to a new container as residual unmixed material may cause a tacky spot on the surface of the casting. Maintain adequate velocity during dispensing to ensure complete mixing.
4. Clean up uncured resin with suitable organic solvent such as MEK or acetone.
5. Allow to cure undisturbed until product is fully gelled or tack-free to the touch.

SHELF LIFE AND STORAGE:

12 months at 25 °C.
Specialty packaging may be less.

Many epoxy resin systems are prone to crystallization as epoxy resin is a super-cooled fluid. This condition may give the product a gritty or grainy appearance (or hazy in clear products). Products in this state will not usually cure to normal and expected properties. In extreme cases it may appear solid and cured. Fluctuating temperatures (within 5 to 50 °C) aggravate this phenomenon. Heating the individual component to 50 to 60 °C while stirring can usually restore products to original state. Storage at 25 +/- 10 °C is optimum for most products.